

**PATENT ASSIGNMENT**

Electronic Version v1.1  
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT												
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT												
<b>CONVEYING PARTY DATA</b>													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Feng-Ning Lee</td> <td>04/13/2007</td> </tr> <tr> <td>Yung-Cheng Chen</td> <td>04/13/2007</td> </tr> <tr> <td>Yao-Hwan Kao</td> <td>04/13/2007</td> </tr> <tr> <td>Li-Jen Ko</td> <td>04/13/2007</td> </tr> <tr> <td>Chin-Hsiang Lin</td> <td>04/13/2007</td> </tr> </tbody> </table>		Name	Execution Date	Feng-Ning Lee	04/13/2007	Yung-Cheng Chen	04/13/2007	Yao-Hwan Kao	04/13/2007	Li-Jen Ko	04/13/2007	Chin-Hsiang Lin	04/13/2007
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Chin-Hsiang Lin	04/13/2007												
<b>RECEIVING PARTY DATA</b>													
<b>Name:</b>	Taiwan Semiconductor Manufacturing Company, Ltd.												
<b>Street Address:</b>	No. 8, Li-Hsin Road 6												
<b>Internal Address:</b>	Science-Based Industrial Park												
<b>City:</b>	Hsin-Chu												
<b>State/Country:</b>	TAIWAN												
<b>Postal Code:</b>	300-77												
<b>PROPERTY NUMBERS Total: 1</b>													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td><b>Application Number:</b></td> <td>11740129</td> </tr> </tbody> </table>		Property Type	Number	<b>Application Number:</b>	11740129								
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<b>Application Number:</b>	11740129												
<b>CORRESPONDENCE DATA</b>													
<b>Fax Number:</b>	(214)200-0853												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
<b>Phone:</b>	972-739-8660												
<b>Email:</b>	bonnie.boyle@haynesboone.com												
<b>Correspondent Name:</b>	Bonnie Boyle												
<b>Address Line 1:</b>	901 Main Street												
<b>Address Line 2:</b>	Suite 3100												
<b>Address Line 4:</b>	Dallas, TEXAS 75202												
<b>ATTORNEY DOCKET NUMBER:</b>	24061.917												

**CH \$40.00 11740129**

NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 3

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**ASSIGNMENT**

WHEREAS, we,

- |     |                 |    |  |
|-----|-----------------|----|--|
| (1) | Feng-Ning Lee   | of | No. 3, Alley 1, Lane 2, Xiangyun St.<br>Longtan Shiang, Taoyuan County 323, Taiwan, R.O.C. |
| (2) | Yung-Cheng Chen | of | No. 29, Lane 588, Shangyi Village<br>Jhubei City, Hsinchu County 302, Taiwan, R.O.C.       |
| (3) | Yao-Hwan Kao    | of | No. 48, Lane 147, Baosin Rd., Baoshan Shiang<br>Hsinchu County 30842, Taiwan, R.O.C.       |
| (4) | Leo Ke          | of | 3F, No. 206, Sec. 1, Shengli 7th St.<br>Zhubei City, Hsinchu County 302, Taiwan, R.O.C.    |
| (5) | Chin-Hsiang Lin | of | No. 37, Lane 393, Min-hu Rd.<br>Hsin-Chu, Taiwan, R.O.C.                                   |

have invented certain improvements in

**PEB EMBEDDED EXPOSURE APPARATUS**

for which we have executed an application for Letters Patent of the United States of America,

         of even date filed herewith; and  
  X   filed on April 25, 2007 and assigned application number 11/740,129; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America,

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whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Feng-Ning Lee

Residence Address: No.3, Alley 1, Lane 2, Xiangyun St.,  
Longtan Shiang, Taoyuan County 325, Taiwan, R.O.C.

Dated: Apr. 13, 2007

Feng-Ning Lee  
Inventor Signature

Inventor Name: Yung-Cheng Chen

Residence Address: No. 29, Lane 588, Shangyi Village  
Jhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: Apr. 13, 2007

Yung-Cheng Chen  
Inventor Signature

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Inventor Name: Yao-Hwan Kao

Residence Address: No. 48, Lane 147, Baosin Rd., Baoshan Shiang  
Hsinchu County 30842, Taiwan, R.O.C.

Dated: April 13, 2007

Yao-Hwan Kao  
Inventor Signature

Inventor Name: Li-Jen Ko

Residence Address: 3F, No. 206, Sec. 1, Shengli 7th St.  
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: Apr 13 2007

Li-Jen Ko  
Inventor Signature

Inventor Name: Chin-Hsiang Lin

Residence Address: No. 37, Lane 393, Min-hu Rd.  
Hsin-Chu, Taiwan, R.O.C.

Dated: April 13, 2007

Chin-Hsiang Lin  
Inventor Signature